ALLIANCE MEMORY MATERIAL DECLARATION

PART NUMBER: AS4C128M32MD4-062BAN	Approved by: quality@alliancememory.com	PART WEIGHT (mg)	244.900

No.	Part Name	Material Name	Material Content (Element)	CAS Number	Material Mass (mg)	Material Mass (%)	Substance wt (%)	Substance wt (mg)
1	Chip	Silicon	Silica	7440-21-3	26.704	10.904%	100%	26.704
2	Substrate	Resin	Thermosetting resin with fiber glass	Trade secret	36.782	15.019%	22.600%	8.313
			Copper	7440-50-8			41.009%	15.084
			Au	7440-57-5			0.909%	0.334
			Nickel	7440-02-0			8.182%	3.009
			Acrylic resin	Trade secret			12.090%	4.447
			Epoxy resin	Trade secret			6.045%	2.223
			Talc containing no asbestos	14807-96-6			2.567%	0.944
			Barium Sulfate	7727-43-7			4.031%	1.483
			Silica, amorphous	7631-86-9			2.567%	0.944
3	Die attach film	Epoxy	Phenol Resin	Trade secret	2.466	1.007%	20.00%	0.493
			Amorphous Silica	7631-86-9			80.00%	1.973
4	Bonding wire	Metal	Au	7440-57-5	2.402	0.981%	99.00%	2.378
			Pd	7440-05-3			1.00%	0.024
5	Molding Compound	Resin	Epoxy Resin	Trade secret	144.427	58.974%	6.00%	8.666
			Phenol Resin	Trade secret			6.00%	8.666
			Carbon Black	1333-86-4			0.30%	0.433
			Silica	60676-86-0			87.70%	126.663
6	Solder ball	Metal	Sn	7440-31-5	32.119	13.115%	96.50%	30.994
			Ag	7440-22-4			3.00%	0.964
			Cu	7440-50-8			0.50%	0.161

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